IEC 61784-2

Edition 3.0 2014-07

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Industrial communication networks – Profiles – Part 2: Additional fieldbus profiles for real-time networks based on ISO/IEC 8802-3

Réseaux de communication industriels – Profils – Partie 2: Profils de bus de terrain supplémentaires pour les réseaux en temps réel basés sur l'ISO/CEI 8802-3

IEC 61784-2:2014-07(en-fr)

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IEC Central Office
3, rue de Varembé
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
Fax: +41 22 919 03 00
info@iec.ch
www.iec.ch

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

COMMISSION ELECTROTECHNIQUE INTERNATIONALE

PRICE CODE XH
CODE PRIX

ICS 35.100.20; 35.240.50

ISBN 978-2-8322-1707-8

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